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PART INFORMATION

Mfg Item Number

AFT05MP075GNR1

Mfg Item Name

TO-270 WB-4 GULL

SUPPLIER Company Name Freescale Semiconductor Inc Company Unique ID 14-141-7928 2018-05-16 Response Date Response Document ID 7563K10873D013A1.11 Contact Name Freescale Semiconductor Inc Contact Title Product Technical Support **Contact Phone** 1-800-521-6274 Contact Email support@freescale.com **Authorized Representative** Daniel Binyon Representative Title **EPP Customer Response** Representative Phone 512-895-3406 Representative Email eppanlst@freescale.com

DECLARATION

EU RoHS
Pb Free
No
HalogenFree
Plating Indicator
EU ROHS Exemption(s)

Fig. 10

www.freescale.com

MANUFACTURING Mfg Item Number AFT05MP075GNR1 Mfg Item Name TO-270 WB-4 GULL Version ALL Weight 1.634800 UoM Unit Volume EACH J-STD-020 MSL Rating 3 Peak Processing Temperature 260 C Max Time at Peak Temperature 40 seconds Number of Processing Cycles



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15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages



Homogeneous Material	Weight					SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Solder Die Attach	0.0101				7a		g				
Solder Die Attach		Lead/Lead Compounds	Lead	7439-92-1		0.0096455	g	955000	95.5	5900	0.59
Solder Die Attach		Metals	Silver, metal	7440-22-4		0.0002525	g	25000	2.5	154	0.0154
Solder Die Attach		Metals	Tin, metal	7440-31-5		0.000202	g	20000	2	123	0.0123
Bonding Wire, Aluminum	0.0107						g				
Bonding Wire, Aluminum		Metals	Aluminum, metal	7429-90-5		0.0107	g	1000000	100	6545	0.6545
Lead Frame Plating	0.0107						g				
Lead Frame Plating		Lead/Lead Compounds	Lead	7439-92-1		0.00000214	g	200	0.02	1	0.0001
Lead Frame Plating		Metals	Tin, metal	7440-31-5		0.01069786	g	999800	99.98	6543	0.6543
Die Encapsulant	0.5338						g				
Die Encapsulant		Solvents, additives, and other materials	Benzophenonetetracarboxylic Acid Dianhydride	2421-28-5		0.03994852	g	74838	7.4838	24436	2.4436
Die Encapsulant		Plastics/polymers	Poly[(o-cresyl glycidyl ether)-co-formaldehyde]	29690-82-2		0.0159793	g	29935	2.9935	9774	0.9774
Die Encapsulant		Plastics/polymers	Proprietary Material-Other Epoxy resins	-		0.0159793	g	29935	2.9935	9774	0.9774
Die Encapsulant		Metals	Magnesium, metal	7439-95-4		0.00095283	g	1785	0.1785	582	0.0582
Die Encapsulant		Solvents, additives, and other materials	Other organic Silicon Compounds	-		0.0028617	g	5361	0.5361	1750	0.175
Die Encapsulant		Glass	Silica, crystalline - quartz (SiO2)	14808-60-7		0.0159793	g	29935	2.9935	9774	0.9774
Die Encapsulant		Glass	Silica, vitreous	60676-86-0		0.42611975	g	798276	79.8276	260655	26.0655
Die Encapsulant		Plastics/polymers	Poly[(phenyl glycidyl ether)-co-dicyclopentadiene]	119345-05-0		0.0159793	g	29935	2.9935	9774	0.9774
Silicon Semiconductor Die	0.0108						g				
Silicon Semiconductor Die		Metals	Gold, metal	7440-57-5		0.00011016	g	10200	1.02	67	0.0067
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%).	-		0.0002138	g	19796	1.9796	130	0.013
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.01047604	g	970004	97.0004	6408	0.6408
Copper Lead Frame, Ni spot	1.0587						g				
Copper Lead Frame, Ni spot		Metals	Copper, metal	7440-50-8		1.02704698	g	970102	97.0102	628251	62.8251
Copper Lead Frame, Ni spot		Solvents, additives, and other materials	Phosphorus, elemental (not containing red allotrope)	7723-14-0		0.00197765	g	1868	0.1868	1209	0.1209
Copper Lead Frame, Ni spot		Metals	Iron, metal	7439-89-6		0.01225763	g	11578	1.1578	7497	0.7497
Copper Lead Frame, Ni spot		Lead/Lead Compounds	Lead	7439-92-1		0.00021492	g	203	0.0203	131	0.0131
Copper Lead Frame, Ni spot		Nickel (external applications only)	Nickel	7440-02-0		0.01720282	g	16249	1.6249	10522	1.0522



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